



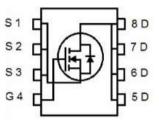
# MJ N-Channel Super Trench II Power MOSFET

#### Description

The series of devices uses Super Trench II technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{DS(ON)}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

#### **General Features**

- ♦ V<sub>DS</sub>=100V,I<sub>D</sub>=60A R<sub>DS(ON)</sub>=8.5mΩ, typical @ V<sub>GS</sub>=10V R<sub>DS(ON)</sub>=10.5mΩ, typical @ V<sub>GS</sub>=4.5V
- Excellent gate charge x RDS(on) product(FOM)
- Very low on-resistance RDS(on)
- ◆ 150°C operating temperature
- Pb-free lead plating

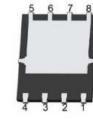


Schematic Diagram

#### Application

- ♦ DC/DC Converter
- $\blacklozenge$  Ideal for high-frequency switching and synchronous rectification

8 7 6 5 MJ 7 2 3 4 Top View



Bottom View

DFN 5X6

### 100% UIS TESTED! 100% ΔVds TESTED!

#### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
P095N10AG	MJXP095N10AG	DFN5X6-8L	1	2	9

### Absolute Maximum Ratings (Tc=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	100	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lo	60	А
Drain Current-Continuous(Tc =100°C)	ID(100℃)	43	А
Pulsed Drain Current	Ідм	240	А
Maximum Power Dissipation	Po	80	W
Derating factor		0.64	W/°C
Single pulse avalanche energy (Note 4)	Eas	260	mJ
Operating Junction and Storage Temperature Range	Тј,Тѕтс	-55 To 150	°C

### Thermal Characteristic

Thermal Resistance, Junction-to-Case	Rejc	1.56	°C/W	
mermal Resistance, Junction-to-Case	Kejc	1.50	C/VV	





## Electrical Characteristics (Tc=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Uni
Off Characteristics		1	1			1
Drain-Source Breakdown Voltage	BVDSS	V <sub>GS</sub> =0V I <sub>D</sub> =250µA	100	-	-	V
Zero Gate Voltage Drain Current	loss	VDS=100V,VGS=0V	-	-	1	μA
Gate-Body Leakage Current	lgss	VDS=±20V,VDS=0V	-	-	±100	nA
On Characteristics (Note 3)		1		1		
Gate Threshold Voltage	VGS(th)	Vos=Vgs,Io=250µA	1.1	1.7	2.5	V
		V <sub>GS</sub> =10V,I <sub>D</sub> =30A	-	8.5	9.5	mΩ
Drain-Source On-State Resistance	Rds(on)	Vgs=4.5V,Id=30A	-	10.5	12.0	mΩ
Forward Transconductance	<b>g</b> FS	Vds=5V,Id=30A	-	45	-	s
Dynamic Characteristics (Note 3)		1		1		1
Input Capacitance	Clss		-	2600	-	PF
Output Capacitance	Coss	V <sub>DS</sub> =50V,V <sub>GS</sub> =0V F=1.0MHz	_	230	-	PF
Reverse Transfer Capacitance	Crss		_	27	_	PF
Switching Characteristics (Note 3)			1	1		1
Turn-on Delay Time	td(on)		-	13	-	nS
Turn-on Rise Time	tr	Vdd=50V,Id=30A	_	10	_	nS
Turn-Off Delay Time	td(off)	Vgs=10V,Rg=1.6Ω	_	30	-	nS
Turn-Off Fall Time	tr		-	8	-	nS
Total Gate Charge	Qg		_	54	-	nC
Gate-Source Charge	Qgs		_	10	-	nC
Gate-Drain Charge	Qgd		_	14		nC
Drain-Source Diode Characteristics		1				
Diode Forward Voltage (Note 2)	Vsd	V <sub>GS</sub> =0V,I <sub>S</sub> =30A	_	-	1.2	V
Diode Forward Current	ls		_	-	60	A
Reverse Recovery Time	trr	T 0700 - 551	_	55		nS
Reverse Recovery Charge	Qrr	TJ=25°C,IF=30A di/dt= 100A/µs <sup>(Note 3)</sup>		98		nC

#### Notes:

① Repetitive Rating: Pulse width limited by maximum junction temperature.

② Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.

3 Guaranteed by design, not subject to production

④ EAS condition : Tj=25℃, VDD=50V, VG=10V, L=0.25mH, Rg=25Ω





# Typical Electrical and Thermal Characteristics

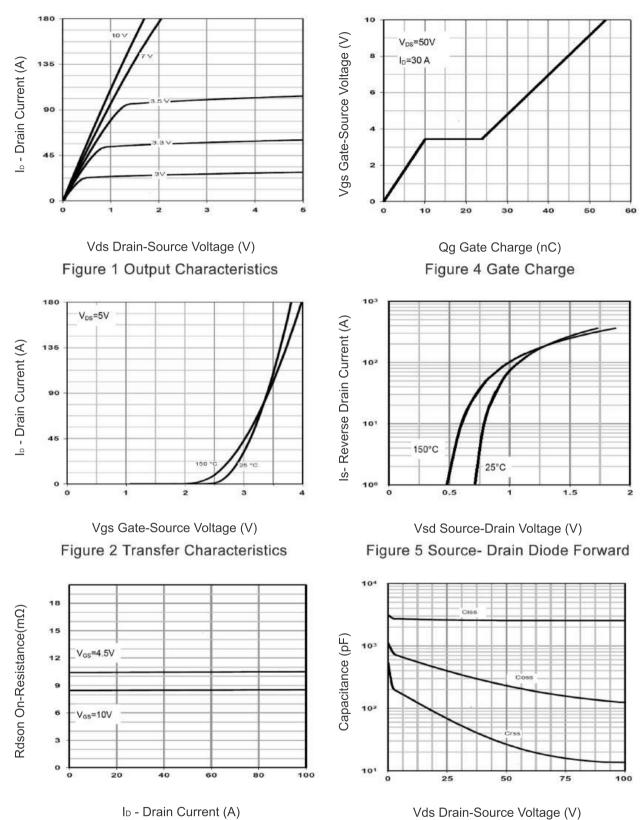
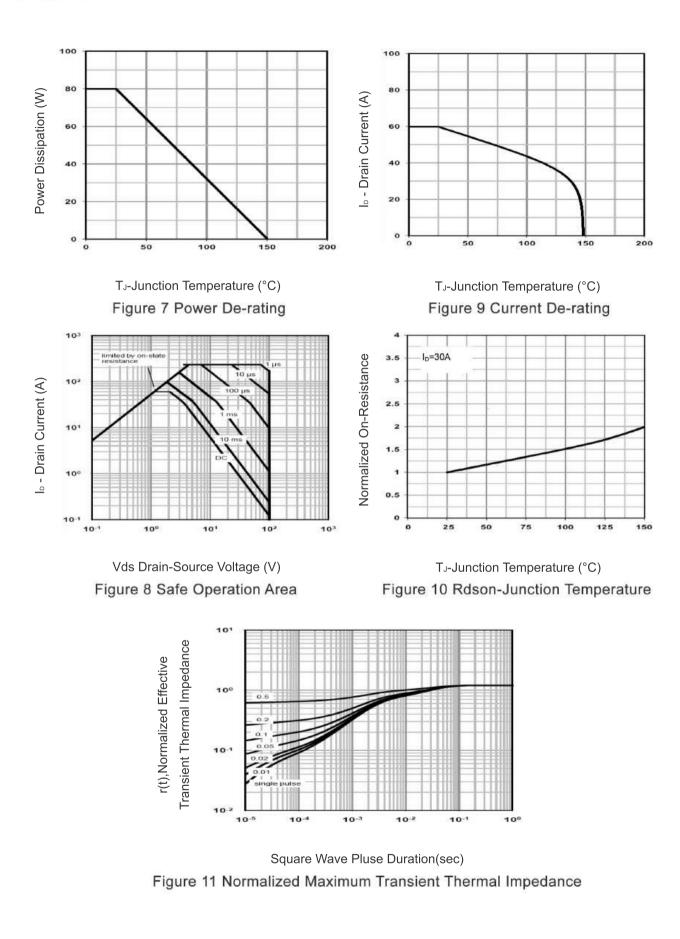


Figure 6 Capacitance vs Vds

Figure 3 Rdson- Drain Current

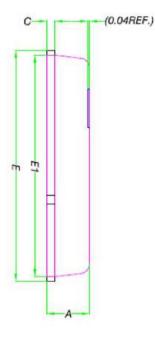


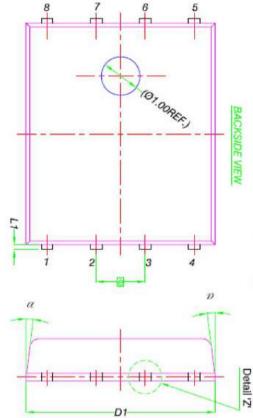


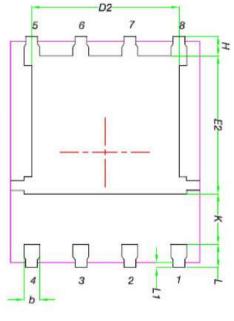


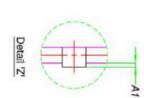




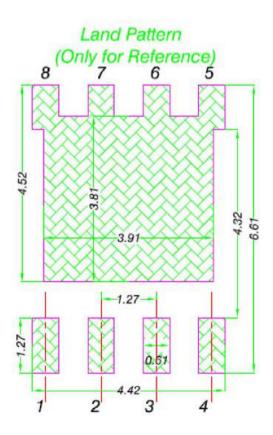








-	MILLIMETERS				
DIM.	MIN.	NOM. 1.00 - 0.41 0.25 4.90 3.81 6.00 5.75 3.58	MAX		
Α	0.90	1.00	1.10		
A1	0	•	0.05		
b	0.33	0.41	0.51		
С	0.20	0.25	0.30		
D1	4.80	4.90	5.00		
D2	3.61	3.81	3.96		
Ε	5.90	6.00	6.10		
E1	5.70	5.75	5.80		
E2	3.38	3.58	3.78		
е	1.27 BSC				
Н	0.41	0.51	0.61		
К	1.10		•		
L	0.51	0.61	0.71		
L1	0.06	0.13	0.20		
α	0°		12		







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